

## PATENT ASSIGNMENT COVER SHEET

Electronic Version v1.1  
 Stylesheet Version v1.2

EPAS ID: PAT4149078

<b>SUBMISSION TYPE:</b>	NEW ASSIGNMENT
<b>NATURE OF CONVEYANCE:</b>	ASSIGNMENT
<b>CONVEYING PARTY DATA</b>	
<b>Name</b>	<b>Execution Date</b>
ALI AYAZI	03/17/2014
KAM-YAN HON	03/17/2014
GIANLORENZO MASINI	03/17/2014
<b>RECEIVING PARTY DATA</b>	
<b>Name:</b>	LUXTERA, INC.
<b>Street Address:</b>	2320 CAMINO VIDA ROBLE
<b>Internal Address:</b>	SUITE 100
<b>City:</b>	CARSLBAD
<b>State/Country:</b>	CALIFORNIA
<b>Postal Code:</b>	92011-1504
<b>PROPERTY NUMBERS Total: 1</b>	
<b>Property Type</b>	<b>Number</b>
Application Number:	14217743
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<b>ATTORNEY DOCKET NUMBER:</b>	27697US02
<b>NAME OF SUBMITTER:</b>	ERICK J. MICHEL
<b>SIGNATURE:</b>	/Erick J. Michel/
<b>DATE SIGNED:</b>	11/18/2016
<b>Total Attachments: 1</b>	
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**ASSIGNMENT**

Whereas, I, **ALI AYAZI, KAM-YAN HON, AND GIANLORENZO MASINI** having agreed to assign the below identified invention to **LUXTERA INC. ("LUX")**, a corporation having its principal place of business at **2320 Camino Vida Roble, Suite 100, Carlsbad, CA 92011-1504** for good and valuable consideration, receipt of which is hereby acknowledged, I do hereby sell, assign, and transfer unto **LUX**, its successors and assigns, the entire right, title, and interest, including the right of priority and action for past infringements in, to and under an application for Letters Patents of the United States entitled:

**METHOD AND SYSTEM FOR A LOW-VOLTAGE INTEGRATED SILICON HIGH-SPEED MODULATOR**

  X   filed herewith and the inventions set forth and described therein, and any and all Letters Patent of the United States and of countries foreign thereto which may be granted thereon or therefor; or

Serial No.: \_\_\_\_\_, filed on \_\_\_\_\_ and the inventions set forth and described therein, and any and all Letters Patent of the United States and of countries foreign thereto which may be granted thereon or therefore, including any continuations, divisionals, reissues, reexaminations, extension, and foreign counterparts of such application and of such Letters Patent;

And for the above consideration, I agree promptly upon request of **LUX**, its successors or assigns, to execute and deliver without further compensation any power of attorney, assignment, application, whether original, continuation, divisional, or reissue, or other papers which may be necessary or desirable fully to secure to **LUX**, its successors and assigns, the inventions described in said application and all patent rights therein, in the United States and in any country foreign thereto, and to cooperate and assist in the prosecution of interference proceedings involving said inventions and in the adjudication or reexamination of said Letters Patent.

Inventor's Signature: \_\_\_\_\_ Date: 3/17/2014  
**ALI AYAZI**

Inventor's Signature: \_\_\_\_\_ Date: 3/17/2014  
**KAM-YAN HON**

Inventor's Signature: \_\_\_\_\_ Date: 3/17/2014  
**GIANLORENZO MASINI**

**PATENT**